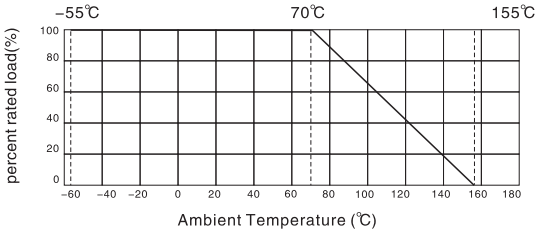
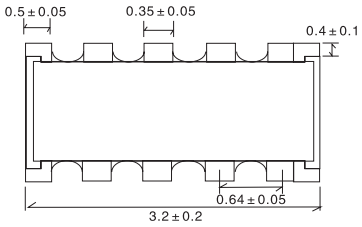
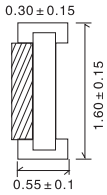
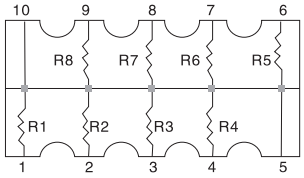
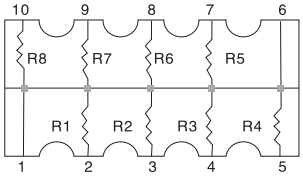
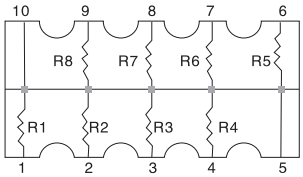
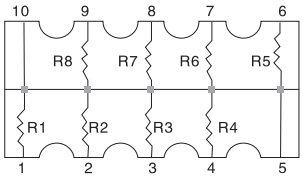
■ 特性 Feature

- 高度密集，多個電阻在一個表貼封裝中
  Hight density,more than 1 resistors in one small case
- 安裝效率高
  Improvement of placement efficency
- 良好的可焊性
  Superior solder ability

■ 降功率曲綫 Derating Curve



■ 規格 & 等效電路 Dinension & Equivalent Circuit Diagram

Type		
Dimension (mm)	 	
Equivalent Circuit Diagram	 R1=R2=R3=R4=R5=R6=R7=R8 10P8 (P Type)	 R1=R2=R3=R4=R5=R6=R7=R8 10S8 (S Type)
Equivalent Circuit Diagram	 R1=R2=R3=R4=R5=R6=R7=R8 10T8 (T Type)	 R1=R2=R3=R4=R5=R6=R7=R8 10E9 (E Type)

■ 性能 Specification

Power tating (70℃)	1/32W, (1/16W可特別提供)
Max.Working Voltage	25V
Max.Overlaoad Volrage	50V
Value Range	10Ω~1MΩ
Tolerance	±1% ±5%
Operating Temperature	−55℃~+155℃
Resistance Value iof 0Ω	<50mΩ
Rated Current of 0Ω	0.5A

■ 測試要求 Test Methods

Teperature Cpefficient	±200PPM/℃
Short−time Overload	±(2.0%+0.05Ω) Max.
Insulation resistance	≥1,000 Mega Ohm
Dielectric withstanding voltage	No evidence of flashover, mechanical damage, arcing or insulation breakdown
Terminal bending	±(1.0% + 0.05Ω) Max.
Soldering heat	±(1.0% + 0.05Ω) Max.
Solder ability	Min 95% coverage
Humidity (Steady State)	±(3.0%+0.1Ω) Max.
Load life	±(3.0%+0.1Ω) Max.